METHOD AND APPARATUS FOR THERMAL DISSIPATION IN AN INFORMATION HANDLING SYSTEM

ABSTRACT OF DISCLOSURE

[0038] A thermal dissipation apparatus includes a primary heat sink. The primary heat sink includes a first base member including a component coupling surface and a secondary heat sink coupling surface, and a plurality of fins extending from the first base member. A secondary heat sink may be provided such that the primary heat sink is operable to provide thermal dissipation in a low profile form factor chassis while the secondary heat sink may be coupled with the primary heat sink to provide more optimal thermal dissipation in a high profile form factor chassis.

Fig. 5b



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